

## Refine Search

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### Search History

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DB=TDBD; PLUR=YES; OP=OR		
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<u>L11</u> L10 and (via or opening	12	<u>L11</u>

<u>L10</u>	L9 and ((insulat\$5 near substrate)	16	<u>L10</u>
<u>L9</u>	(die or chip) same (((conductor\$4) near- ("side surface" or "side surfaces")) and ("upper surface" or "lower surface"))	69	<u>L9</u>
<u>L8</u>	L7	5	<u>L8</u>
<u>L7</u>	L6 and ("conductive epoxy" near7 (conductor\$ or metal))	5	<u>L7</u>
<u>L6</u>	L5 and ((via or opening) near7 substrate)	47	<u>L6</u>
<u>L5</u>	("conductive epoxy" NEAR6 (CHIP OR DIE)) and "lead frame"	197	<u>L5</u>
<u>L4</u>	L3 and ((insulat\$5 near substrate) same "metal foil") and (chip or die)	0	<u>L4</u>
<u>L3</u>	"conductive epoxy" and "lead frame"	563	<u>L3</u>
<u>L2</u>	5780928 and "conductive epoxy"	0	<u>L2</u>
<u>L1</u>	5780928	18	<u>L1</u>

END OF SEARCH HISTORY

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